

Presentation of Specification to TSG or WG

Presentation to: TSG-RAN Meeting #10

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Abstract of document:

This technical report captures the results of the work on the work item “Low Chip Rate TDD Layer2 and Layer3 Protocol Aspects”. It includes the services provided by the physical layer and the layer 2/3 functionality for support of the 1.28 Mcps TDD. It is identified which modifications will be required in order to enable the layer 1 characteristics and key features 1.28Mcps TDD based on the protocol structure existing for UTRA TDD / FDD.

Changes since last presentation to TSG-RAN Meeting:

Sections on handover procedures, cell (re)selection, AC/ASC concept, MAC functions for 1.28Mcps TDD and compressed mode to monitor 1.28Mcps TDD are added in this technical report, and some editorial corrections are also made on it..

Outstanding Issues:

Contentious Issues: